

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A metal/ceramic bonding substrate comprising:

 a ceramic substrate;

 a metal circuit plate bonded to one side of said ceramic substrate;

 a heat sink ~~member~~ plate of a metal, one side of which is bonded to the other side of said ceramic substrate; and

 a work-hardened layer of the same material as said metal, formed on the other side of said heat sink ~~member~~ plate, said work-hardened layer being formed by colliding ceramic or glass balls with the other side of said heat sink plate.

2. (currently amended) A metal/ceramic bonding substrate as set forth in claim 1, wherein said work-hardened layer is formed ~~by work hardening a surface of said heat sink member~~ by shot peening.

3. (currently amended) A metal/ceramic bonding substrate as set forth in claim 1, wherein a warpage of the other side of said heat sink ~~member~~ plate is -200 micrometers or more, assuming that said warpage is a difference in height between a center and edge of the other side of said heat sink ~~member~~ plate and is positive (+) when the other side of said heat sink ~~member~~ plate warps so as to be convex and negative (-) when the other side of said heat sink ~~member~~ plate warps so as to be concave.

4. (currently amended) A metal/ceramic bonding substrate as set forth in claim 1, wherein a warpage of the other side of said heat sink ~~member~~ plate is in the range of from -100 to +500 micrometers, assuming that said warpage is a difference in height between a center and edge of the other side of said heat sink ~~member~~ plate and is positive (+) when the other side of said heat sink ~~member~~ plate warps so as to be convex and negative (-) when the other side of said heat sink ~~member~~ plate warps so as to be concave.

5. (currently amended) A metal/ceramic bonding substrate as set forth in claim 1, wherein a warpage of the other side of said heat sink ~~member~~ plate is in the range of from 0 to +200 micrometers, assuming that said warpage is a difference in height between a center and edge of the other side of said heat sink ~~member~~ plate and is positive (+) when the other side of said heat sink ~~member~~ plate warps so as to be convex and negative (-) when the other side of said heat sink ~~member~~ plate warps so as to be concave.

6. (currently amended) A metal/ceramic bonding substrate as set forth in claim 1, wherein said metal circuit plate and said heat sink ~~member~~ plate contact said ceramic substrate to be bonded directly to said ceramic substrate.

7. (original) A power module comprising:

 a metal/ceramic bonding substrate as set forth in claim 1;
 and

 a semiconductor chip soldered on said metal circuit plate
 of said metal/ceramic bonding substrate.

10. (new) A metal/ceramic bonding substrate as set forth in

claim 1, wherein said metal is aluminum or an aluminum alloy.

11. (new) A metal/ceramic bonding substrate as set forth in
claim 6, wherein said metal is aluminum or an aluminum alloy.

12. (new) A metal/ceramic bonding substrate as set forth in
claim 1, wherein said metal is copper.